| ASSOCIATION CONNECTIN<br>ELECTRONICS INDUSTRIE | Material Composition © Copyright 2005. IPC, international and Pan-Ar | Bannockb                  | urn, Illinois. A                 | ll rights reserved un<br>ntions. | nder both               | This docume<br>level parts, t                                      | ent is a declara<br>he declaration | ion of the s<br>encompasse | ubstances<br>es all lower  | within the manufactur<br>r level materials for w | rer listed i<br>hich the r      | tem. Note: i<br>nanufacturer | f the item is an as<br>has engineering | sembly with lower responsibility. |
|--|--|---------------------------|----------------------------------|----------------------------------|-------------------------|--|------------------------------------|----------------------------|----------------------------|--|---------------------------------|------------------------------|--|-----------------------------------|
| 1752-21.1                                      |  |                           |                                  |                                  | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materi |                                    |                            |                            |  | als and Mfg Information         |                              |  |                                   |
| Supplier Inforn                                | ation  |                           |                                  |                                  |                         |  |                                    |                            |                            |  |                                 |                              |  |                                   |
| Company name*                                  |  |                           | Company unique ID                |                                  |                         |  | Unique ID Authority                |                            |                            |  | Response Date*                  |                              |  |                                   |
| onsemi   |  |                           |                                  |                                  |                         |  |                                    |                            |                            |  | 2025-06-07                      |                              |  |                                   |
| Contact Name                                   |  |                           | Title - Contact                  |                                  |                         |  | Phone - Contact*                   |                            |                            |  | Email - Contact*                |                              |  |                                   |
| Product-Env-Stewards                           |  |                           | Product Enviro Compliance        |                                  |                         |  | NA                                 |                            |                            |  | Product-Env-Stewards@onsemi.com |                              |  |                                   |
| Authorized Represe                             | ntative*   | Title - Representative    |                                  |                                  |                         | Phone - Representative*  |                                    |                            |                            | Email - Representative*                          |                                 |                              |  |                                   |
| Product-Env-Stewa                              | ırds   | Product Enviro Compliance |                                  |                                  |                         | NA   |                                    |                            |                            | Product-Env-Stewards@onsemi.com                  |                                 |                              |  |                                   |
| Request  | Requester Item Number Mfr Item                                       |                           | n Number Mfr Item Name           |                                  |                         |  | Effective Date                     | e Version                  | Version Manufacturing Site |  |                                 | Weight*                      | UOM                                    | Unit Type                         |
|  |  | NB6L11MMNR2G              |                                  | 1:2 CML FANOUT                   |                         |  | 2025-06-07                         | MY1                        |                            |  | 23.69                           | mg                           | Each                                   |                                   |
| Manufacturing                                  | Proccess Information   | 1                         |                                  |                                  |                         |  |                                    |                            |                            |  |                                 |                              |  |                                   |
| Terminal Plating / Grid Array Material         |  |                           | erminal Base Alloy J-STD-020 MSL |                                  | L Rating                | Peak Process Body Temperature                                      |                                    | e Max Time at Peak         | Tempera                    | ture Numb  | er of Reflow Cyc                | eles                         |  |                                   |
| Matte Tin (Sn) - annealed CU A                 |  |                           | U Alloy                          | y 1                              |                         |  | 260 C 30                           |                            |                            | 30   | seconds 3                       |                              |  |                                   |
| Comments                                       |  |                           |                                  |                                  |                         |  |                                    |                            |                            |  |                                 |                              |  |                                   |
| evel 1 - maximum t                             | ime at peak temperature o  | luring sol                | dering is 10-3                   | 0 seconds                        |                         |  |                                    |                            |                            |  |                                 |                              |  |                                   |
| For more informati                             | on regarding material con  | position <b>j</b>         | please refer to                  | page 3                           |                         |  |                                    |                            |                            |  |                                 |                              |  |                                   |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl by that the (DEHP), Disobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance           | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|---------------------|------------------|--------|---------|-----------------|
| Die                  | 0.25   | mg              | Supplier | Silicon (Si)        | 7440-21-3        |        | 0.25    | mg              |
| Die Attach           | 0.65   | mg              | Supplier | Silver (Ag)         | 7440-22-4        |        | 0.4875  | mg              |
|                      |        |                 | Supplier | Epoxy resins        | 129915-35-1      |        | 0.1625  | mg              |
| Lead Frame           | 10.08  | mg              | Supplier | Tin (Sn)            | 7440-31-5        |        | 0.0252  | mg              |
|                      |        |                 | Supplier | Zinc (Zn)           | 7440-66-6        |        | 0.0222  | mg              |
|                      |        |                 | Supplier | Chromium (Cr)       | 7440-47-3        |        | 0.0252  | mg              |
|                      |        |                 | Supplier | Copper (Cu)         | 7440-50-8        |        | 10.0074 | mg              |
| Mold Compound-Black  | 12.09  | mg              |          | Epoxy resin         | proprietary data |        | 0.5682  | mg              |
|                      |        |                 | Supplier | Phenol Resin        | Proprietary Data |        | 0.5682  | mg              |
|                      |        |                 | Supplier | Carbon Black (C)    | 1333-86-4        |        | 0.0121  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2) | 60676-86-0       |        | 10.9415 | mg              |
| Plating              | 0.48   | mg              | Supplier | Palladium (Pd)      | 7440-05-3        |        | 0.0115  | mg              |
|                      |        |                 | В        | Nickel (Ni)         | 7440-02-0        |        | 0.4224  | mg              |
|                      |        |                 | Supplier | Gold (Au)           | 7440-57-5        |        | 0.0461  | mg              |
| Wire Bond - Au       | 0.14   | mg              | Supplier | Gold (Au)           | 7440-57-5        |        | 0.14    | mg              |